

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Wei-Lien Yang	06/22/2012
RECEIVING PARTY DATA	
Name:	Intel Corporation
Street Address:	2200 Mission College Blvd.
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13535823
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	TROP, PRUNER & HU, P.C.
Address Line 1:	1616 S. VOSS RD., SUITE 750
Address Line 4:	HOUSTON, TEXAS 77057-2631
ATTORNEY DOCKET NUMBER:	ITL.2705US (P42925)
NAME OF SUBMITTER:	John C. Garza
Total Attachments: 2 source=2705-assignment#page1.tif source=2705-assignment#page2.tif	

CH \$40.00 13535823

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Wei-Lien Yang

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

LOW POWER DATA RECOVERY

(I hereby authorize and request my attorney, associated with Customer Number 47795, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on 06/28/2012 as

United States Application Number 13/535,823 and

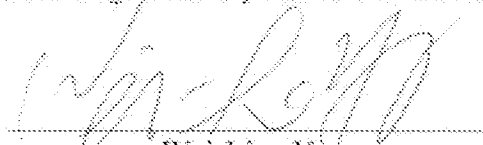
which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and

improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Wei-Lien Yang

6/22/12

(Today's Date)